

COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
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APPLICABLE STANDARD									
RATING	OPERATING TEMPERATURE RANGE	-35°C TO 85 °C(NOTE1)			STORAGE TEMPERATURE RANGE	-10°C TO 60 °C(NOTE2)			
	VOLTAGE	300V AC			APPLICABLE CONNECTOR	MDF6— * DS—3.5C			
	CURRENT	7A							

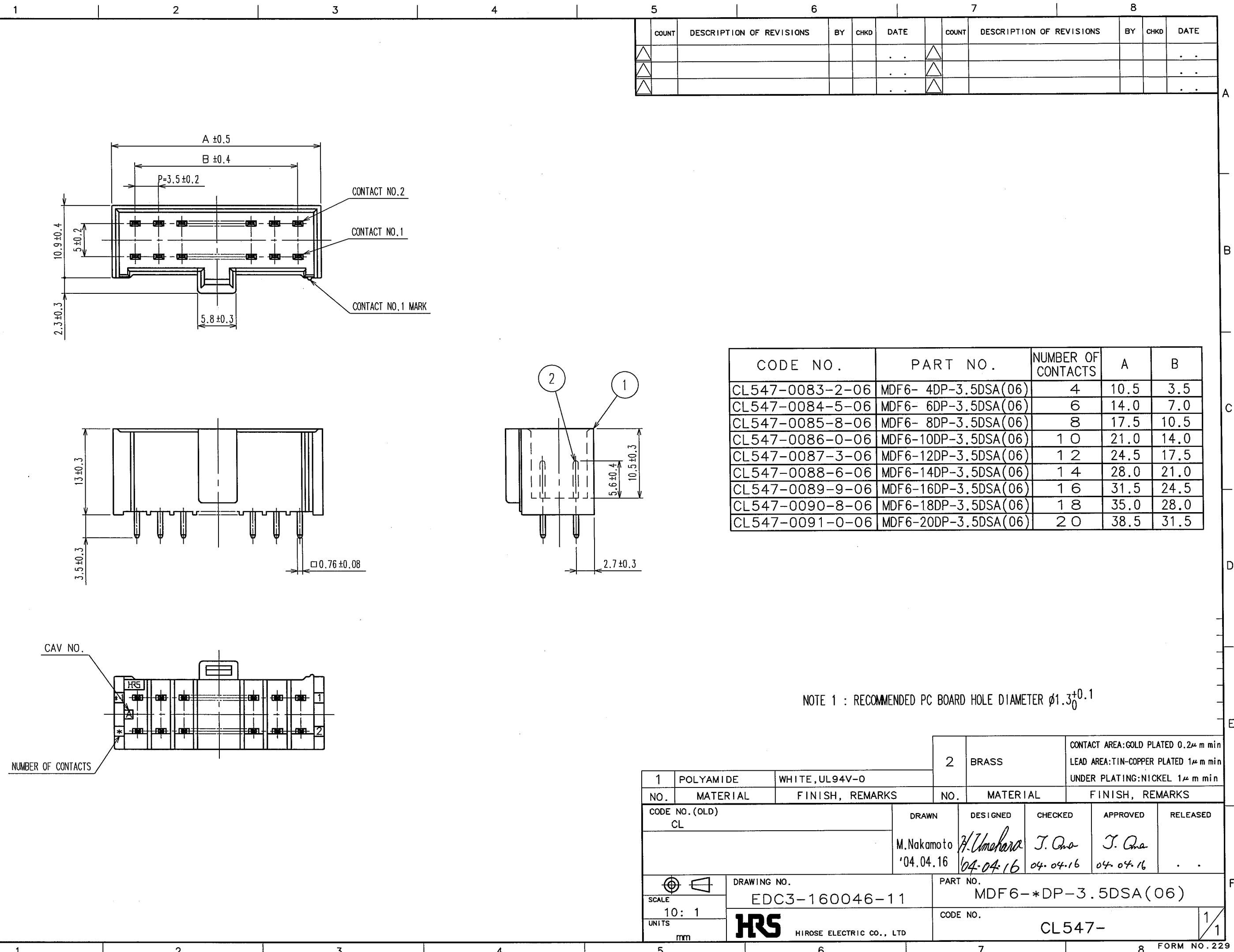
SPECIFICATIONS						
ITEM	TEST METHOD	REQUIREMENTS	QT	AT		
CONSTRUCTION						
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	x	x		
MARKING	CONFIRMED VISUALLY.		x	x		
ELECTRICAL CHARACTERISTICS						
CONTACT RESISTANCE	100 mA (DC OR 1000 Hz).	30 mΩ MAX.	x	—		
INSULATION RESISTANCE	500 V DC.	1000 MΩ MIN.	x	—		
VOLTAGE PROOF	1500 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	x	—		
MECHANICAL CHARACTERISTICS						
MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS, OF PARTS.	x	—		
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS, OF PARTS.	x	—		
SHOCK	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS, OF PARTS.	x	—		
ENVIRONMENTAL CHARACTERISTICS						
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 TO 95 %, 96 h.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS, OF PARTS.	x	—		
RAPID CHANGE OF TEMPERATURE	TEMPERATURE: -55→ 5 TO 35→85→ 5 TO 35 °C TIME: 30→10 TO 15→30→10 TO 15 min UNDER 5 CYCLES.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS, OF PARTS.	x	—		
RESISTANCE TO SOLDERING HEAT	SOLDER TEMPERATURE 260±3 °C, FOR IMMERSION DURATION 10 s.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	x	—		
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE 230±5 °C FOR IMMERSION DURATION 5 s.	SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	x	—		
REMARKS						
NOTE1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD,OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION.		DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
Unless otherwise specified, refer to JIS C 5402.		M.Nakamoto '04.04.16	H. Umehara '04.04.16	J. Ona 04.04.16	J. Ona 04.04.16	
Note QT: Qualification Test AT: Assurance Test x: Applicable Test						
HRS HIROSE ELECTRIC CO., LTD.		SPECIFICATION SHEET		PART NO. MDF6— * DP—3.5DSA (06)		
CODE NO.(OLD) CL	DRAWING NO. ELC4—160046—11	CODE NO. CL547		1/1		

TO

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DRAWING FOR REFERENCE: This is subject to change without notice

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CODE NO.	PART NO.	NUMBER OF CONTACTS	A	B
CL547-0083-2-06	MDF6- 4DP-3.5DSA(06)	4	10.5	3.5
CL547-0084-5-06	MDF6- 6DP-3.5DSA(06)	6	14.0	7.0
CL547-0085-8-06	MDF6- 8DP-3.5DSA(06)	8	17.5	10.5
CL547-0086-0-06	MDF6-10DP-3.5DSA(06)	10	21.0	14.0
CL547-0087-3-06	MDF6-12DP-3.5DSA(06)	12	24.5	17.5
CL547-0088-6-06	MDF6-14DP-3.5DSA(06)	14	28.0	21.0
CL547-0089-9-06	MDF6-16DP-3.5DSA(06)	16	31.5	24.5
CL547-0090-8-06	MDF6-18DP-3.5DSA(06)	18	35.0	28.0
CL547-0091-0-06	MDF6-20DP-3.5DSA(06)	20	38.5	31.5

NOTE 1 : RECOMMENDED PC BOARD HOLE DIAMETER $\phi 1.3^{+0.1}_0$

1	POLYAMIDE	WHITE, UL94V-0	2	BRASS	CONTACT AREA: GOLD PLATED 0.2 μ m min LEAD AREA: TIN-COPPER PLATED 1 μ m min UNDER PLATING: NICKEL 1 μ m min
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
CODE NO. (OLD) CL		DRAWN M. Nakamoto '04.04.16	DESIGNED H. Umehara '04.04.16	CHECKED J. Ono 04.04.16	APPROVED J. Ono 04.04.16
SCALE 10: 1		DRAWING NO. EDC3-160046-11		PART NO. MDF6-*DP-3.5DSA(06)	
UNITS mm		HRS HIROSE ELECTRIC CO., LTD		CODE NO. CL547-	